

TECH DATA SHEET

ILR-1402 – HIGH TEMPERATURE STABLE RESIN (FM51-26)



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DESCRIPTION

ILR-1402 is a high molecular weight, curable oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications. The resin is supplied pre-dissolved in anisole (methoxy benzene) for ease of incorporation. The unique ILR-1402 joins the nature of a thermoplastic resin (flexibility, high strength) and a thermoset resin (curability, hydrophobicity, ease of customer use) together with superior electrical properties for the next generation of high frequency applications.

HIGHLIGHTS

- Very low material shrinkages
- Flexible / high strength
- Curability
- Very low modulus
- Hydrophobic / low water absorption
- Ease of customer use

TYPICAL PHYSICAL AND CHEMICAL PROPERTIES

PROPERTY	METHOD	RESULT
TGA, °C	Td(5%)	472.5
CTE (α_1), ppm/°C	TMA	35
Tg, °C	TMA	179.6
	DMA	199.7
Modulus @25C, MPa	DMA	193
Dk	AET, 20GHz	2.5
Df	AET, 20GHz	0.0025

Data is for reference only and we recommend use of this data as a guide..

RECOMMENDED APPLICATION:

R1402 is suggested for use in applications that require high temperature resin performance such as CCL.

INSTRUCTIONS FOR USE:

APPLICATION - ILR-1402 MAY BE APPLIED BY NORMAL MEANS – SPIN COATING, DISPENSE TECHNIQUES OR EVEN JETTING.

DRYING - ILR-1402 DRYING CONDITION : 30~60MIN @100°C

CURING - ILR-1402 CURE CONDITION : 1HR~2HRS @200°C HOMOPOLYMERIZATION

CONTACT:

REQUEST A SAMPLE OR PLACE AN ORDER

Customer Support

☎ 858-348-1122

✉ support@designermoleculesinc.com

REF: DMI Part Number: R1402